Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832
Email & Skype: info@chipsmall.com Web: www.chipsmall.com
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

Characterization Sheet (Multilayer Ceramic Chip Capacitors)

C2012X8L1E155K125AB

TDK Item Description : C2012X8L1E155KT****

Lead Free
Halogen Free
REACH
RoHS COMPLIANT

Application & Main Feature

Commercial Grade (High Temperature Application))

Series

C2012 [EIA 0805]

Dimensions

L	2.00mm +/-0.2mm
W	1.25mm +/-0.2mm
T	1.25mm +/-0.2mm
B	0.20mm Min.
G	0.50mm Min.

Temperature Characteristic

X8L (-55 to 150 degC +15,-40%)

Rated Voltage

1E(25Vdc)

Capacitance

1.5uF

Capacitance Tolerance

K (+/-10%)

Dissipation Factor

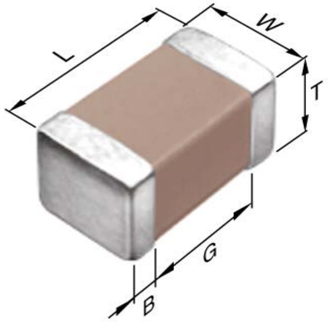
5% Max.

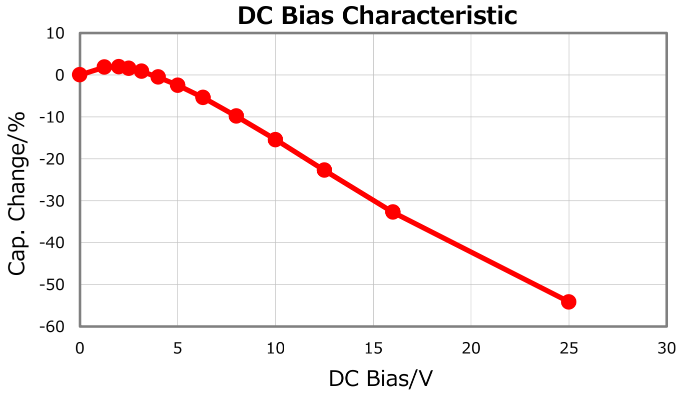
Insulation Resistance

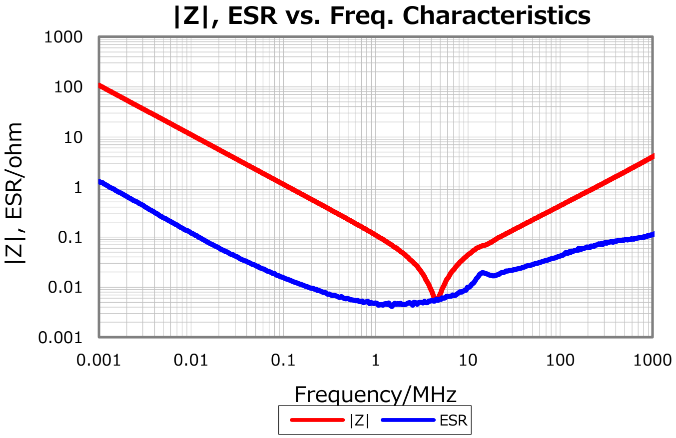
333Mohm Min.

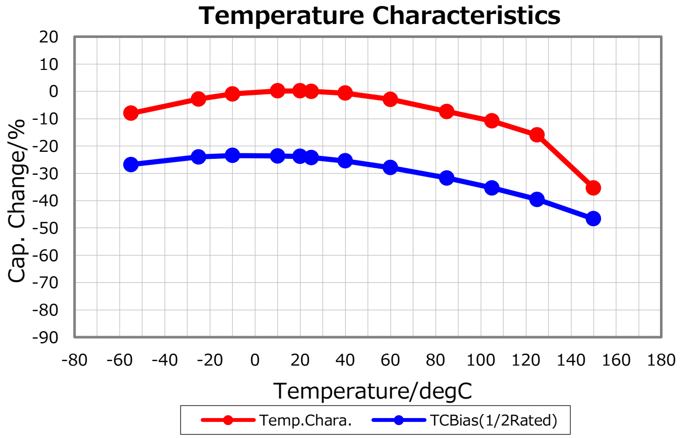
AEC-Q200

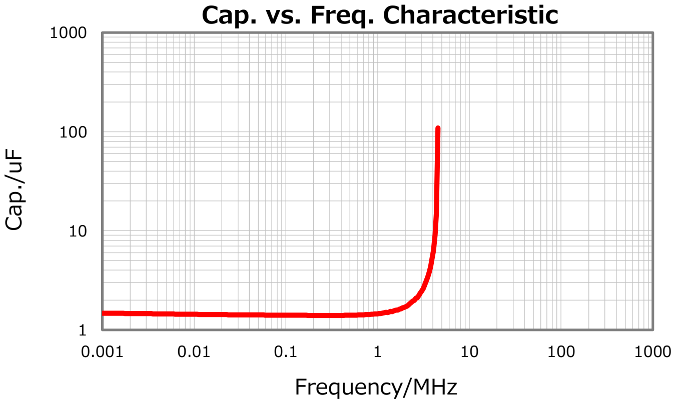
Not Applicable

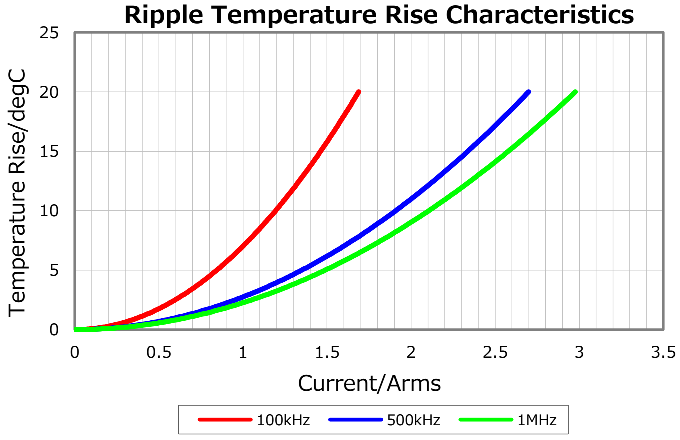



DC Bias Characteristic


|Z|, ESR vs. Freq. Characteristics


Temperature Characteristics


Cap. vs. Freq. Characteristic


Ripple Temperature Rise Characteristics

TDK

All specifications are subject to change without notice.

June 19, 2017